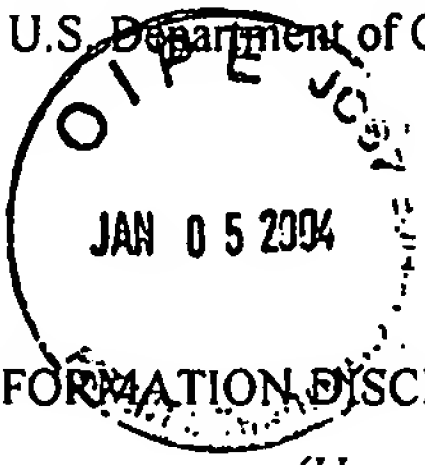
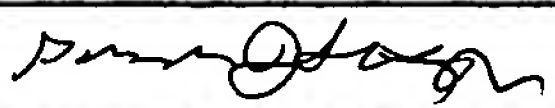
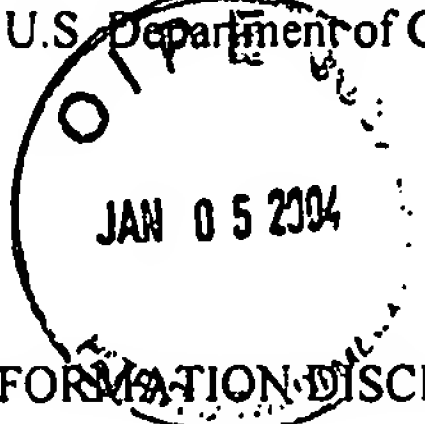


U.S. Department of Commerce, Patent and Trademark Office  INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use several sheets if necessary)	Application No.:	09/974,571
	Filing Date:	October 9, 2001
	First Named Inventor:	Peter G. Borden
	Group Art Unit:	2877
	Examiner Name:	Unknown
	Confirmation No.:	1003
	Attorney Docket No.:	BOX013 US

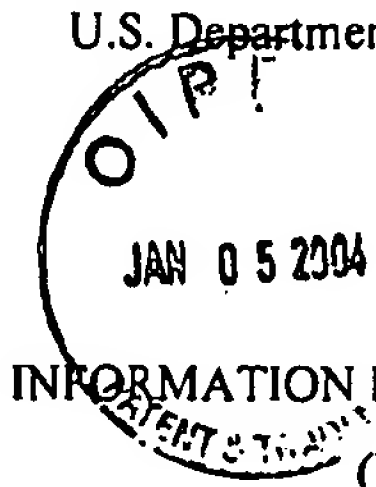
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*Examiner Initials		Document Number	Date	Name	Class	Subclass	Filing Date if Appropriate
PD	1.	4,273,421	6/16/81	Gurtler	356	432	
PD	2.	4,854,710	8/8/89	Opsal et al.	356	432	
PD	3.	4,211,488	7/8/80	Kleinknecht	356	433	
PD	4.	5,379,109	1/3/95	Gaskill et al.	356	445	
PD	5.	6,489,801	12/3/02	Borden et al.	324	766	
PD	6.	5,966,019	10/12/99	Borden	324	752	
PD	7.	5,377,006	12/27/94	Nakata	356	349	
PD	8.	5,706,094	1/6/98	Maris	356	432	
PD	9.	6,118,533	9/12/00	Banet et al.	356	345	
PD	10.	6,323,951	11/27/01	Borden et al.	356	502	
PD	11.	6,426,644	7/30/02	Borden et al.	324	765	
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PD	16.	5,228,776	7/20/93	Smith et al.	374	5	
PD	17.	4,255,971	3/17/81	Rosencwaig	73	606	
PD	18.	4,579,463	4/1/86	Rosencwaig et al.	374	57	
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PD	20.	4,636,088	1/13/87	Rosencwaig et al.	374	5	
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Examiner: 	Date Considered: 6/10/04
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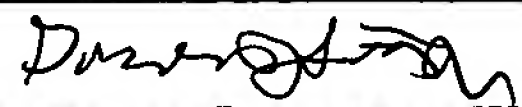
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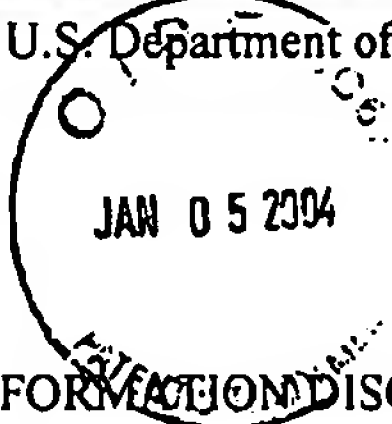
26	5,761,082	6/2/98	Miura-Mattausch	703	14	
27	4,996,659	2/26/91	Yamaguchi et al.	714	736	
28	6,154,280	11/2/00	Borden	356	376	
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30	5,883,518	3/16/99	Borden	324	752	
31	5,877,860	3/2/99	Borden	356	376	
32	4,652,757	3/24/87	Carver	250	360	
33	5,978,074	11/2/99	Opsal et al.	356	72	
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35	6,268,916	7/31/01	Lee et al.	356	432	
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39	2003/96436A1	5/22/03	Satya et al.	438	11	
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44	6,281,027	9/28/01	Wei et al.	438	14	
45	4,521,118	06/00/85	Rosencwaig	374	5	
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49	4,634,290	1/6/87	Rosencwaig	374	5	
50	4,552,510	6/11/85	Rosencwaig	374	7	
51	4,571,685	02/18/86	Kamoshida	364	468	


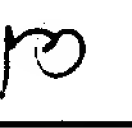
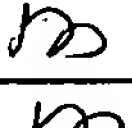
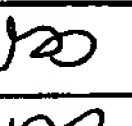
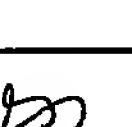

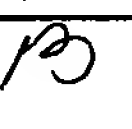
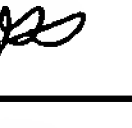
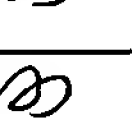

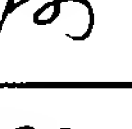
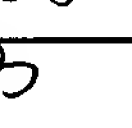

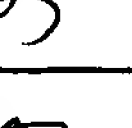
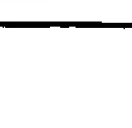




Examiner: <i>P. J. O'Brien</i>	Date Considered: <i>6/10/04</i>
* Examiner: Initial if reference is considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with your communication with applicant.	

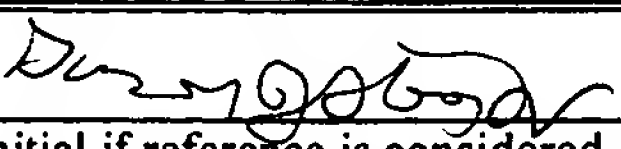
U.S. Department of Commerce, Patent and Trademark Office  INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use several sheets if necessary)	Application No.:	09/974,571
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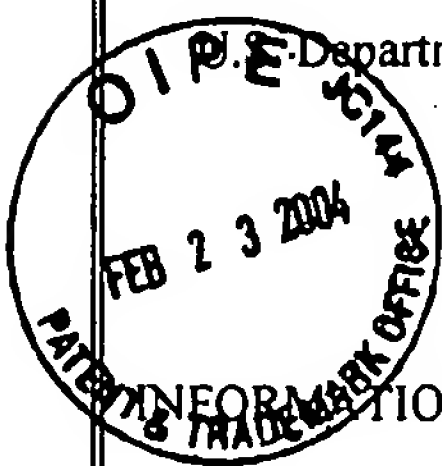
Foreign Patent Documents								
							Translation	
		Document	Date	Country	Class	Subclass	Yes	No
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ms	56	Opsal et al. "Thermal-Wave Detection and Thin-Film Thickness Measurements with Laser Beam Deflection", Applied Optics, Vol. 22, No. 20, Oct. 1983, pp. 3169-3176						
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ms	59	W. L. Smith et al. "Ion Implant Monitoring With Thermal Wave Technology," Nuclear Instruments and Methods Physics Research, B21, (1987), 537-541.						
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 Department of Commerce, Patent and Trademark Office INFORMATION DISCLOSURE STATEMENT BY APPLICANT (Use several sheets if necessary)	Application No.:	09/974,571
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	Group Art Unit:	2877
	Examiner Name:	Smith, Zandra B.
	Confirmation No.:	1003
	Attorney Docket No.:	BOX013 US

U.S. Patent Documents							
*Examiner Initials		Document Number	Date	Name	Class	Subclass	Filing Date if Appropriate
PS	1.	2001/0015937	8/23/01	Yamaguchi et al.	369	13	
PS	2.	6,020,964	2/1/00	Loopstra et al.	356	500	
PS	3.	6,400,454	6/4/02	Noguchi et al.	356	237	
Foreign Patent Documents							
							Translation
		Document	Date	Country	Class	Subclass	Yes No
Other Art (Including Author, Title, Date, Pertinent Pages, Etc.)							

Examiner: <i>Dmitry G. G. G.</i>	Date Considered: <i>6/10/04</i>
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